

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

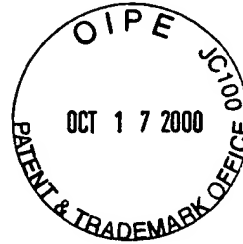
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JLW

In re application of

ANTHONY J. KONECNI ET AL.

Serial No. 08/988,686 (TI-22166)

Filed December 11, 1997



For: METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE

Art Unit 2823

Examiner K. Eaton

Commissioner for Patents
Washington, D. C. 20231

Sir:

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AMENDMENT UNDER 37 C.F.R. 1.111

In response to the Office action dated August 30, 2000, please amend the above identified application as follows:

In the claims:

Amend claim 21 as follows:

21. (Amended) A method of fabricating an electronic device having a first electrically conductive structure electrically connected to a second electrically conductive structure situated over a semiconductor substrate, said method comprising the steps of:

forming said first electrically conductive structure;

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